VISCOM
vision technology

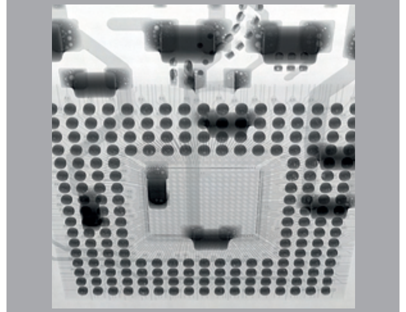
X8068

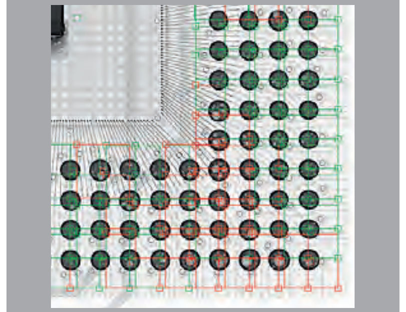
Versatile X-ray inspection for SMT/electronics

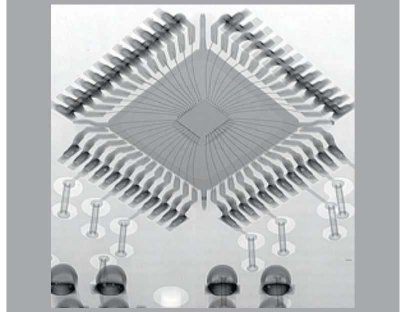
MXI

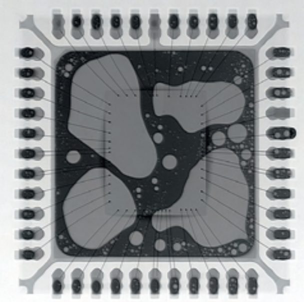
With Quality Uplink!

Fast, convenient, high performance


BGA overview under angled radiation


BGA defect analysis


QFP under angled radiation


QFP orthogonally radiated

High resolution X-ray inspection – made by Viscom

Two inspection concepts in one system: Viscom XMC and Viscom SI

Powerful open microfocus transmission tube

Flat panel detectors for brilliant image quality

Highest magnifications

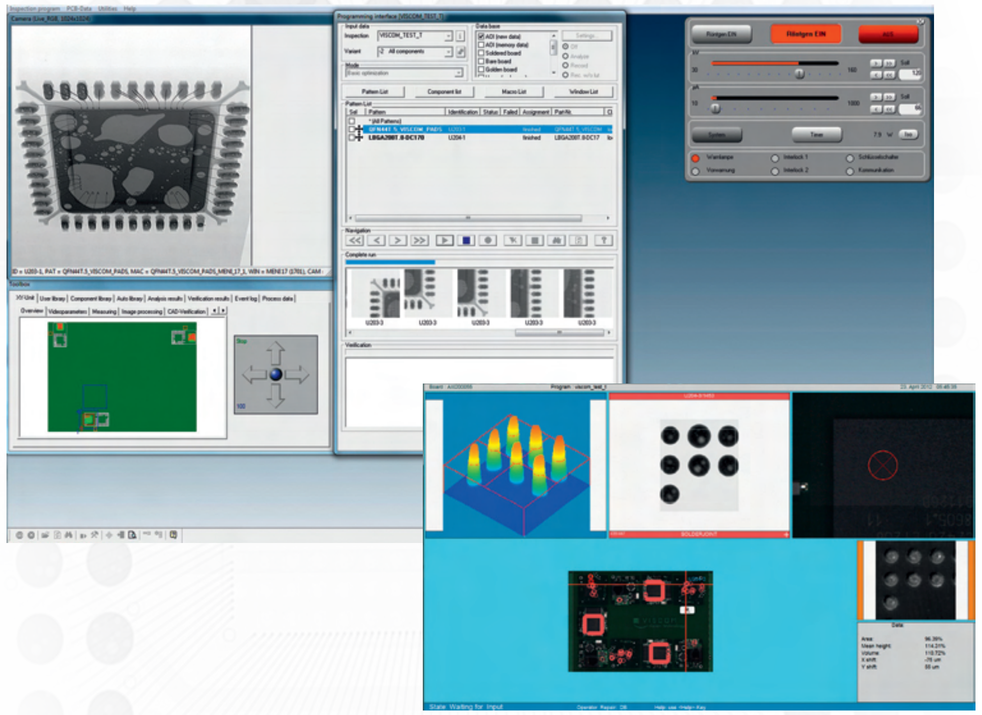
Large inspection objects up to a diameter of 722 mm (28.4") can be inspected

Intuitive operation and comprehensive analysis functions

Unique Quality Uplink for simplified classification and process control

Worldwide, competent service on-site, hotline and remote maintenance

Customer support area on the Viscom website



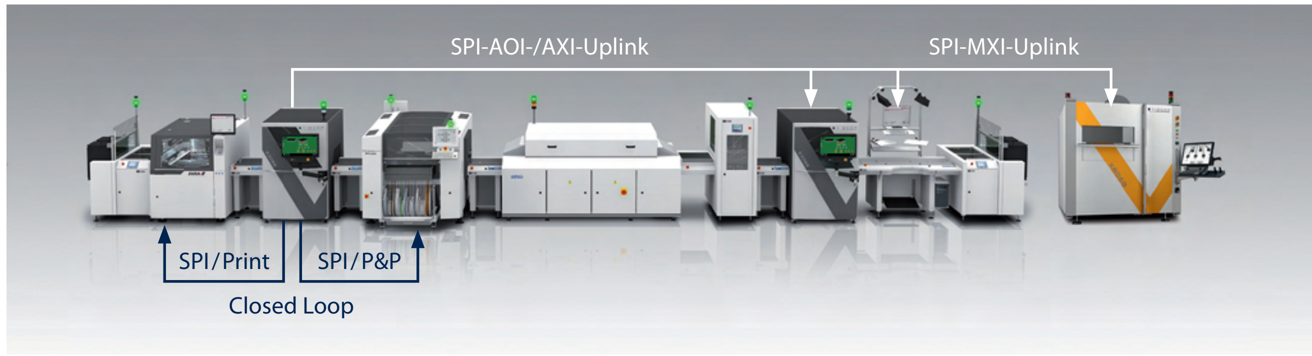
Brilliant image quality, easiest operation, comprehensive analysis

The X8068 reliably inspects the **entire range of inspection objects** up to a diameter of 722 mm (28.4"). The open X-ray tube ensures the **highest resolution and detail recognition in first-class image quality**. Thus even the smallest defective structures are reliably detected. The system delivers with a mature technology which demonstrates its full strength in the interaction of all the hardware and software components. The **user-friendly new IPS monitor** depicts the X-ray results in the **best quality**, independent of the viewing angle. In order to attain the largest possible inspection area, the detector swivel range is up to 60 degrees. System **operation is easy and convenient**.

The special strength of the X8068: It combines **two inspection concepts**, Viscom XMC and Viscom SI, **in one inspection system**. Therefore the Viscom XMC software is available for **special inspections** or non-standard components. Thanks to **intuitive operation and comprehensive automatic analysis functions**, inspection objects can be **quickly and precisely** checked.

The proven SI software of the Viscom X7056 family is employed for the **fully automatic X-ray analysis**. It culminates **over 30 years' experience** in assembly inspection and is specially suited for SMD production. This means the **unique Viscom Quality Uplink** can also be used. Through the **linking of inspection results** from SPI, AOI, AXI and MXI, this function provides a **simplified classification** and **effective process control**. For example, all inspection data from the Viscom 3D solder paste inspection can be displayed on the verification station of the X8068. **Defect causes are easier to track down** and **process optimization is simplified**.

Whether hidden soldered connections in SMD assembly, power electronics or non-destructive testing of non-standard components – the X-ray inspection system X8068 guarantees the highest flexibility. The application scope reaches from random sample analysis and special inspection of individual components, up to automatic start-up support and series inspection. Even large inspection objects, such as printed circuit board panels, are inspected quickly and reliably. The brilliant image quality, automatic analysis routines and convenient operation make this system the reliable partner in quality control.



VISCOM
vision technology

Technical Specifications

X8068

X-ray technology

X-ray tube	Open microfocus transmission tube Viscom XT9160-TED
High voltage	10 - 160 kV
Tube current	5 - 1000 µA
Target power	Max. 40 W
Geometric magnification	> 2500 times
Resolution	< 4 µm (proved by JIMA tests)
Flat panel detector	5,7" x 4,6" FPD 14 Bit
X-ray cabinet	In compliance with the German X-Ray Regulations (RöV) regarding fully protected devices. Radiation leakage rate < 1 µSv/h

Software

User interface	Viscom XMC and Viscom SI
Optional	BGA analysis software BGA-S Surface analysis software (voiding calculation) ACA-S THT analysis software THT-S Wire sweep analysis software WSA-S Viscom Quality Uplink (to Viscom AOI, AXI, MXI, SPI)

System computer

Operating system	Windows®
Processor	Intel® Core™ i7

Sample handling

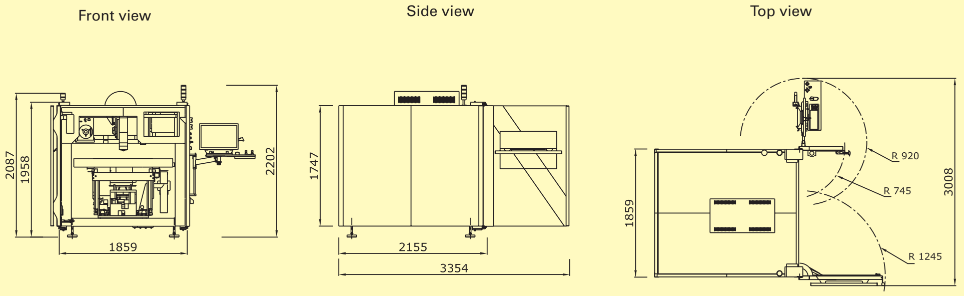
Manipulator	5 axes with sample table
Horizontal X/Y-axis	Travel range: 720 x 1000 mm (28.4" x 39.4")
Vertical Z-axis	Travel range: 320 mm (12.6")
Detector axis	0° - 60° pivoting
Rotational axis	n x 360°
Max. test piece size	722 mm (28.4") (diameter)
Max. test piece weight	15 kg (33 lbs)
Test piece change	Front window (manual/automatic)

Inspection speed

Variable

Other system data

Power requirements	230 V (other voltages on request), 1P/N/PE, 10 A
System dimension	1859 x 2202 x 2155 mm (73.19" x 86.69 x 84.84") (W x H x D)
Weight	< 3200 kg (7055 lbs)



Dimensions in mm

Headquarters:
Viscom AG
Carl-Buderus-Straße 9 - 15 · 30455 Hanover · Germany
Tel.: +49 511 94996-0 · Fax: +49 511 94996-900
info@viscom.com · www.viscom.com

Visit our website to find international subsidiaries and representatives in Europe, USA and Asia:

www.viscom.com